

PCN# : P382A
Issue Date : Sep. 26, 2013

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Dec. 25, 2013

Expected First Date Code of Changed Product : 1404

Description of Change (From) :
Currently using 2.0mils Au wire and Die attach using EN4620K Epoxy

Description of Change (To) :
Change to 2.0mils Cu wire and Die attach using QMI519 Epoxy

Reason for Change:
Au to Cu wire conversion for better electrical and thermal performance and epoxy standardization.

Affected Product(s):

FDMS2572	FDMS2672	FDMS2734
FDMS3572	FDMS3672	FDMS5672

Qualification Plan	Device	Package	Process	No. of Lots
F20120165	FDMS3572	MLDAMA08	Mosfet	1

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/77
High Temperature Storage Life	150C	JESD22-A103	2000 hrs	0/77
Power Cycle	125°C TJC, delta Tj of 100 C, 2 min on, 2 min off	JESD22-A122	10k cycles	0/77
Highly Accelerated Stress Test	130C, 85%RH	JESD22-A110	192 hrs	0/77
MSL1	260C, 3 cycles	J-STD_020		0/22
Die Shear	500g	MIL-STD-883-2019		0/5
Construction Analysis				0/2
Bond Shear	15g	AEC-Q100-001		0/5
Bond Pull	3.0g	JESD22-C100		0/5

Qualification Plan	Device	Package	Process	No. of Lots
F20120165	FDMS2672	MLDAMA08	Mosfet	1

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/77
High Temperature Storage Life	150C	JESD22-A103	2000 hrs	0/77
Power Cycle	125°C TJC, delta Tj of 100 C, 2 min on, 2 min off	JESD22-A122	10k cycles	0/77
Highly Accelerated Stress Test	130C, 85%RH	JESD22-A110	192 hrs	0/77
MSL1	260C, 3 cycles	J-STD_020		0/22
Die Shear	500g	MIL-STD-883-2019		0/5
Construction Analysis				0/2
Bond Shear	15g	AEC-Q100-001		0/5
Bond Pull	3.0g	JESD22-C100		0/5

Qualification Plan	Device	Package	Process	No. of Lots
F20120165	FDMS5672	MLDAMA08	Mosfet	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/231
High Temperature Reverse Bias Test	150°C Tj, 80% of Rated BV	JESD22-A108	1000 hrs	0/77
High Temperature Gate Bias Test	150°C Tj, 100% of rated VGS	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/77
High Temperature Storage Life	150C	JESD22-A103	2000 hrs	0/77
Power Cycle	125°C TJC, delta Tj of 100 C, 2 min on, 2 min off	JESD22-A122	10k cycles	0/77
Highly Accelerated Stress Test	130C, 85%RH	JESD22-A110	192 hrs	0/77
MSL1	260C, 3 cycles	J-STD_020		0/22
Die Shear	500g	MIL-STD-883-2019		0/5
Construction Analysis				0/2
Bond Shear	15g	AEC-Q100-001		0/5
Bond Pull	3.0g	JESD22-C100		0/5